UNIQUE DIRECT PROCESSING PLATFORM TECHNOLOGY



μDALPTM

ATLANT 3D technology is based on the state-of-the-art $\mu DALP^{TM}$ (Microreactor Direct Atomic Layer Processing), which use a micronozzle to deliver reactive gases that create self-controlled surface chemical reactions allowing direct patterning and structuring within designated areas. $\mu DALP^{TM}$ enables material innovation and rapid prototyping manufacturing on a wafer level to work with a versatile group of materials for electronic and optical applications.

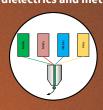


Illustration of µDALP™ nozzle geometry and process principles (left), ellipsometry thickness map and low-energy ion scattering spectroscopy map of Pt deposition Ref: <u>Small Methods</u> **2022**, 6, 2101546

Direct Patterning & Complex Designs with Arbitrary Shapes



Wide materials selection of the commercially available materials precursors, e.g. for dielectrics and metals



Micrometer scale Line Width



No vacuum required



Atomic Scale Thickness Variability & Precise Gradient Control



Deposition on Complex Surface Geometries and on Sensitive Materials, e.g. glass or polymers



MARKETS AND APPLICATION DOMAINS

Fundamental & Industrial R&D

Optics & Photonics

Microelectronics

Emerging Technologies

CONTACT DETAILS Umberto Martinez, PhD Head of Business Development

um@atlant3d.com

+45 71 99 09 54

